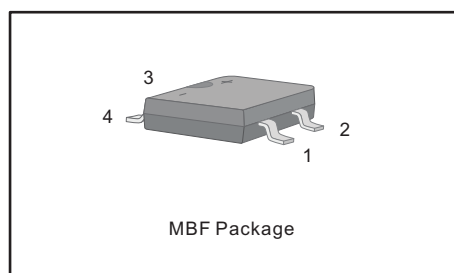


2A SURFACE MOUNT SCHOTTKY BRIDGE
FEATURES:

- Reverse Voltage - 40 to 200 V
- Forward Current - 2 A
- High Surge Current Capability
- Designed for Surface Mount Application

PINNING

PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)


MECHANICAL DATA

- Case: MBF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 75mg 0.0026oz

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	MB24F	MB26F	MB28F	MB210F	MB220F	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	40	60	80	100	200	V
Maximum RMS voltage	V_{RMS}	28	42	56	70	140	V
Maximum DC Blocking Voltage	V_{DC}	40	60	80	100	200	V
Maximum Average Forward Rectified Current at $T_c = 90\text{ }^\circ\text{C}$	$I_{F(AV)}$	2.0					A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	50			40		A
Max Instantaneous Forward Voltage at 2 A	V_F	0.55	0.70	0.85			V
Maximum DC Reverse Current at Rated DC Reverse Voltage $T_a = 25\text{ }^\circ\text{C}$ $T_a = 100\text{ }^\circ\text{C}$	I_R	0.5 10			0.3 5		mA
Typical Junction Capacitance ¹⁾	C_j	220	80				pF
Typical Thermal Resistance ²⁾	$R_{\theta JA}$	75					$^\circ\text{C/W}$
Operating Junction Temperature Range	T_j	-55 ~ +125					$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-55 ~ +150					$^\circ\text{C}$

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm) copper pad.

Fig.1 Forward Current Derating Curve

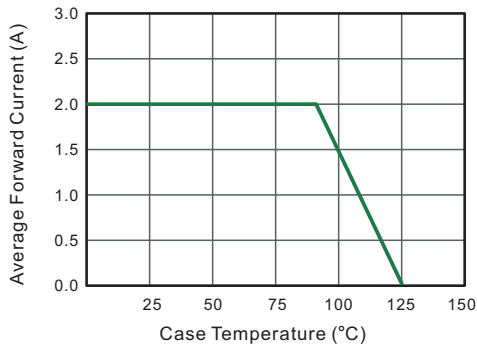


Fig.2 Typical Reverse Characteristics

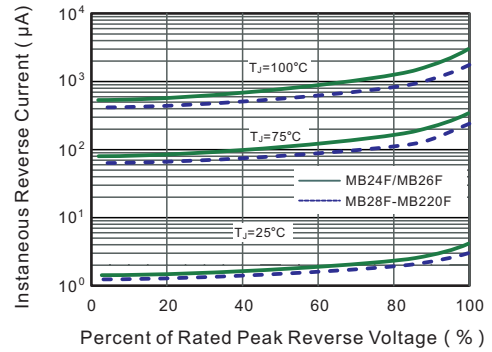


Fig.3 Typical Forward Characteristic

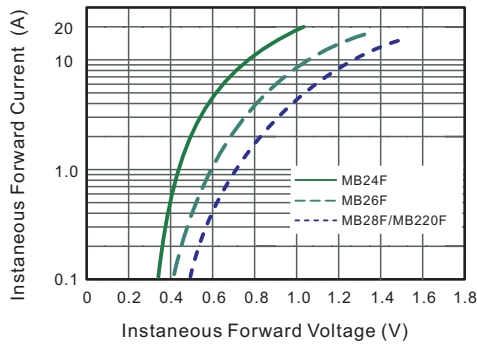


Fig.4 Typical Junction Capacitance

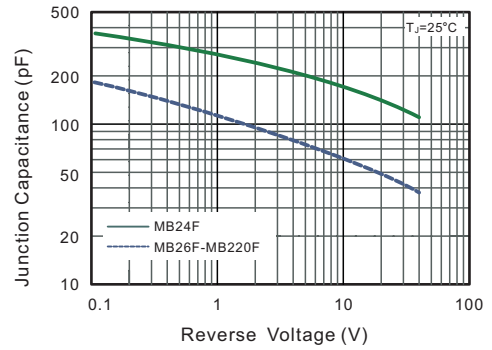


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

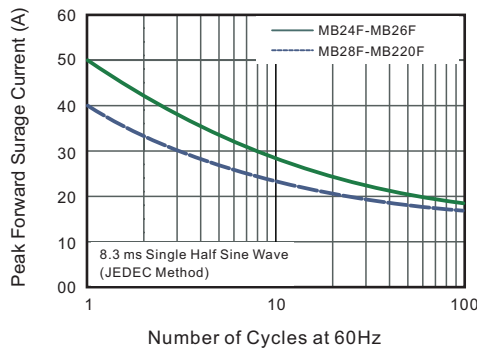
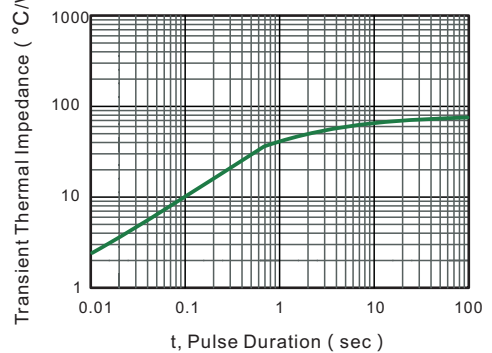
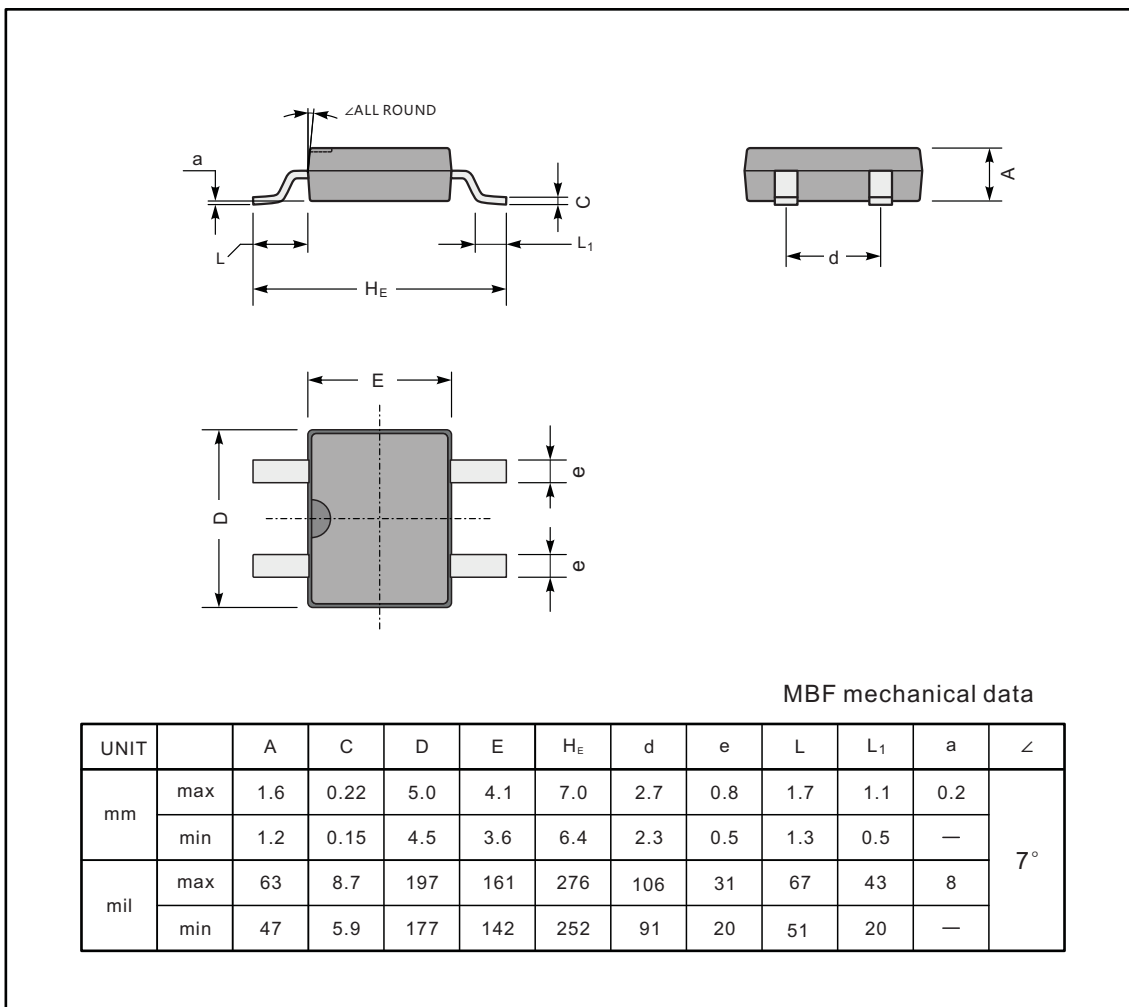
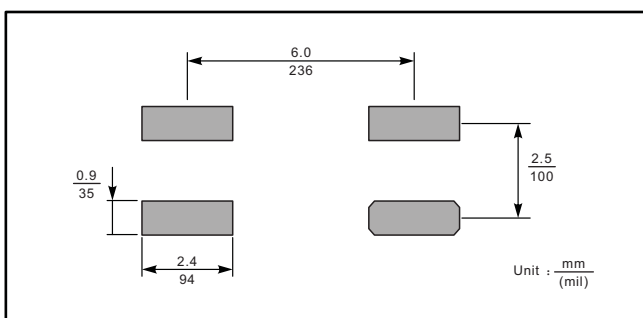


Fig.6- Typical Transient Thermal Impedance



PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

MBF

The recommended mounting pad size

Marking

Type number	Marking code
MB24F	MB24F
MB26F	MB26F
MB28F	MB28F
MB210F	MB210F
MB220F	MB220F

